

Global Epoxy Resin Encapsulation Adhesive for Electronic Products Market 2026 by Manufacturers, Regions, Type and Application, Forecast to 2032

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Abstracts

According to our (Global Info Research) latest study, the global Epoxy Resin Encapsulation Adhesive for Electronic Products market size was valued at US\$ 1608 million in 2025 and is forecast to a readjusted size of US\$ 2465 million by 2032 with a CAGR of 6.3% during review period.

In 2025, the global production of epoxy resin encapsulation adhesive for electronic products reached approximately 189,100 tons, with an average global market price of around US\$8,000/ton. In the same year, the global total production capacity of epoxy resin encapsulation adhesive for electronic products reached 20,000 tons. The industry average gross profit margin of this product reached 36%. Epoxy resin encapsulation adhesive for electronic products is an electronic encapsulation material made primarily of epoxy resin, combined with curing agents, fillers, accelerators, flame retardants, and functional additives. It is mainly used for encapsulation, potting, underfilling, and protection of semiconductors, PCBs, power modules, LEDs, automotive electronics, sensors, IGBTs, and consumer electronics devices. Its core function is to provide electronic components with insulation, moisture protection, corrosion resistance, thermal shock resistance, mechanical protection, and thermal management capabilities, thereby improving the reliability and lifespan of electronic products. As electronic devices evolve towards higher power, miniaturization, higher frequency and speed, and higher integration, modern epoxy encapsulation adhesives have evolved from traditional protective materials into key functional materials affecting chip heat dissipation, signal stability, and long-term reliability.

The upstream of the epoxy resin encapsulation adhesive for electronic products industry chain mainly includes suppliers of epoxy resins, curing agents, silica powder, alumina,

boron nitride and other fillers, as well as flame retardants, coupling agents and functional additives. The midstream consists of encapsulation adhesive manufacturers responsible for formulation design, modification, mixing, low-stressing, high thermal conductivity and semiconductor-grade purification. The downstream covers semiconductor packaging and testing, power devices, automotive electronics, LEDs, consumer electronics, industrial control, communication equipment, AI servers and new energy fields. Currently, the industry's technological barriers are mainly concentrated in low CTE, high thermal conductivity, high flowability, low ionic impurities, high reliability and advanced packaging compatibility. Therefore, leading companies usually possess material formulation, application verification and customer certification capabilities.

From an industry outlook perspective, the epoxy resin encapsulation adhesive for electronic products industry is in a continuous upgrading phase, with growth driven primarily by the development of AI chips, advanced packaging, new energy vehicles, electric drive systems, SiC/GaN power semiconductors, 5G base stations and high-performance computing. The rapidly increasing demand for high thermal conductivity, low warpage, and low stress EMC, particularly in HBM, GPUs, AI servers, and automotive power modules, has made advanced packaging EMC one of the fastest-growing segments. Future industry development will focus on new material systems that offer high thermal conductivity, are green and halogen-free, have ultra-low dielectric properties, high resistance to humidity and heat, and are compatible with Chiplet and advanced heterogeneous packaging. Asia, especially mainland China, Taiwan, Japan, and South Korea, will continue to dominate global demand and production capacity.

This report is a detailed and comprehensive analysis for global Epoxy Resin Encapsulation Adhesive for Electronic Products market. Both quantitative and qualitative analyses are presented by manufacturers, by region & country, by Type and by Application. As the market is constantly changing, this report explores the competition, supply and demand trends, as well as key factors that contribute to its changing demands across many markets. Company profiles and product examples of selected competitors, along with market share estimates of some of the selected leaders for the year 2025, are provided.

Key Features:

Global Epoxy Resin Encapsulation Adhesive for Electronic Products market size and forecasts, in consumption value (\$ Million), sales quantity (Tons), and average selling prices (US\$/Ton), 2021-2032

Global Epoxy Resin Encapsulation Adhesive for Electronic Products market size and forecasts by region and country, in consumption value (\$ Million), sales quantity (Tons), and average selling prices (US\$/Ton), 2021-2032

Global Epoxy Resin Encapsulation Adhesive for Electronic Products market size and forecasts, by Type and by Application, in consumption value (\$ Million), sales quantity (Tons), and average selling prices (US\$/Ton), 2021-2032

Global Epoxy Resin Encapsulation Adhesive for Electronic Products market shares of main players, shipments in revenue (\$ Million), sales quantity (Tons), and ASP (US\$/Ton), 2021-2026

The Primary Objectives in This Report Are:

- To determine the size of the total market opportunity of global and key countries

- To assess the growth potential for Epoxy Resin Encapsulation Adhesive for Electronic Products

- To forecast future growth in each product and end-use market

- To assess competitive factors affecting the marketplace

This report profiles key players in the global Epoxy Resin Encapsulation Adhesive for Electronic Products market based on the following parameters - company overview, sales quantity, revenue, price, gross margin, product portfolio, geographical presence, and key developments. Key companies covered as a part of this study include 3M, Henkel, Parker LORD, SolEpoxy, Epic Resins, Robnor ResinLab, Guangdong Anders Industrial Co., Ltd., Shantou Niche-Tech Kaiser Co., Ltd., Dongguan Huachuang Electronic Materials Co., Ltd., Guangdong Wanmu New Material Technology Co., Ltd., etc.

This report also provides key insights about market drivers, restraints, opportunities, new product launches or approvals.

Market Segmentation

Epoxy Resin Encapsulation Adhesive for Electronic Products market is split by Type

and by Application. For the period 2021-2032, the growth among segments provides accurate calculations and forecasts for consumption value by Type, and by Application in terms of volume and value. This analysis can help you expand your business by targeting qualified niche markets.

Market segment by Type

One-component

Two-component

Market segment by Curing Method

Room Temperature Curing

Heat Curing

UV Curing

Others

Market segment by Resin System

Bisphenol A Type

Phenolic Novolac Type

Biphenyl Type

Cyanate Ester Modified Type

Siloxane Modified Type

Market segment by Application

Consumer Electronics

Automotive Electronics

Medical Electronics

Industrial

Others

Major players covered

3M

Henkel

Parker LORD

SolEpoxy

Epic Resins

Robnor ResinLab

Guangdong Anders Industrial Co., Ltd.

Shantou Niche-Tech Kaiser Co., Ltd.

Dongguan Huachuang Electronic Materials Co., Ltd.

Guangdong Wanmu New Material Technology Co., Ltd.

Beijing Kmt Technology Co., Ltd

Yongdeji Technology (Suzhou) Co., Ltd.

Shanghai Dodi Polymer Material Co., Ltd.

Hubei Huitian New Materials Co., Ltd.

Dongguan Sains Industrial Co., Ltd.

Shin-Etsu Chemical

Sumitomo Bakelite

NAMICS Corporation

Resonac

Master Bond

Epoxy Technology

EpoxySet

United Resin

DELO

Panacol

Electrolube

Bostik

Market segment by region, regional analysis covers

North America (United States, Canada, and Mexico)

Europe (Germany, France, United Kingdom, Russia, Italy, and Rest of Europe)

Asia-Pacific (China, Japan, Korea, India, Southeast Asia, and Australia)

South America (Brazil, Argentina, Colombia, and Rest of South America)

Middle East & Africa (Saudi Arabia, UAE, Egypt, South Africa, and Rest of

Middle East & Africa)

The content of the study subjects, includes a total of 15 chapters:

Chapter 1, to describe Epoxy Resin Encapsulation Adhesive for Electronic Products product scope, market overview, market estimation caveats and base year.

Chapter 2, to profile the top manufacturers of Epoxy Resin Encapsulation Adhesive for Electronic Products, with price, sales quantity, revenue, and global market share of Epoxy Resin Encapsulation Adhesive for Electronic Products from 2021 to 2026.

Chapter 3, the Epoxy Resin Encapsulation Adhesive for Electronic Products competitive situation, sales quantity, revenue, and global market share of top manufacturers are analyzed emphatically by landscape contrast.

Chapter 4, the Epoxy Resin Encapsulation Adhesive for Electronic Products breakdown data are shown at the regional level, to show the sales quantity, consumption value, and growth by regions, from 2021 to 2032.

Chapter 5 and 6, to segment the sales by Type and by Application, with sales market share and growth rate by Type, by Application, from 2021 to 2032.

Chapter 7, 8, 9, 10 and 11, to break the sales data at the country level, with sales quantity, consumption value, and market share for key countries in the world, from 2021 to 2026. and Epoxy Resin Encapsulation Adhesive for Electronic Products market forecast, by regions, by Type, and by Application, with sales and revenue, from 2027 to 2032.

Chapter 12, market dynamics, drivers, restraints, trends, and Porters Five Forces analysis.

Chapter 13, the key raw materials and key suppliers, and industry chain of Epoxy Resin Encapsulation Adhesive for Electronic Products.

Chapter 14 and 15, to describe Epoxy Resin Encapsulation Adhesive for Electronic Products sales channel, distributors, customers, research findings

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